# Monthly LabAdviser update: 7/1 2014

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| Updated Subject  | Contributor | Link to the updated pages |
| **Mask Design**Hint for mask design using CleWin5 + how to freely access CleWin5 | **Jesper Hanberg@ danchip** | [Mask Design with CleWin5](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Mask_Design) |
| **News in LabAdviser**Slides from customer meeting December 2013 | **Anders M. Jørgensen@ Danchip** | [Link to slides from customer meeting from front page](http://labadviser.danchip.dtu.dk/index.php/Main_Page) |
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| **Alcatel**QC data limits | **Katharina Nilson@ danchip** | [QC limits for Alcatel](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Alcatel) |
| **Wordentech**QC data limits | **Katharina Nilson@ danchip** | [QC limits for Wordentech](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Wordentec) |
| **KOH**QC data limits | **Karen Birkelund@** | [QC limits for KOH](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/KOH_Etch) |
| **DRIE-pegasus**QC data limits | **Jonas M. Lindhard@ danchip** | [QC limits DRIE Pegasus](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/processA) |
| **ASE**QC data limits | **Jonas M. Lindhard@ danchip** | [QC limits for ASE](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon/Si_etch_using_ASE) |
| **AOE**QC data limits | **Berit G. Herstrøm@ danchip** | [QC limits for AOE](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide/SiO2_etch_using_AOE) |
| **RIE2**QC data limits | **Berit G. Herstrøm@ danchip** | [QC limits for RIE2 Si etch](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon/Si_etch_using_RIE1_or_RIE2)[QC limits for RIE2 SiO2 etch](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide/SiO2_etch_using_RIE1_or_RIE2) |
| **PECVD2**QC data limits | **Berit G. Herstrøm@ danchip** | [QC limits for PECVD2](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/III-V_Process/thin_film_dep/pecvd2/PECVD2_programs#SiO2stdLow) |
| **PECVD3**QC data limits | **Berit G. Herstrøm@ danchip** | [QC limits for PECVD3 oxide](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide/Deposition_of_Silicon_Oxide_using_PECVD#Recipes_on_PECVD3_for_deposition_of_silicon_oxides)[QC limits for PECVD3 nitride](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Nitride/Deposition_of_Silicon_Nitride_using_PECVD#Recipes_on_PECVD3_for_deposition_of_silicon_nitride_and_silicon_oxynitride) |
| **Furnace Bor predep + drive-in**QC data limits | **Mikkel D. Mar@ danchip** | [QC limits for Furnace Boron predep-drive in](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/A1_Furnace_Boron_drive-in)Under construction |
| **Furnace Phosphor predep**QC data limits | **Mikkel D. Mar@ danchip** | [QC limits for Furnace Phosphor drive-in](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/A3_Phosphor_Drive-in_furnace) |
| **LPCVD nitride 4”**QC data limits | **Pernille V. Larsen@ danchip** | [QC limits LPCVD nitride 4"](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Nitride/Deposition_of_Silicon_Nitride_using_LPCVD/Standard_recipes%2C_QC_limits_and_results_for_the_4%22_nitride_furnace) |
| **LPCVD nitride 6”**QC data limits | **Pernille V. Larsen@ danchip** | [QC limits for LPCVD nitride 6"](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Nitride/Deposition_of_Silicon_Nitride_using_LPCVD/Standard_recipes%2C_QC_limits_and_results_for_the_6%22_nitride_furnace) |
| **LPCVD PolySi 4”**QC data limits | **Pernille V. Larsen@ danchip** | [QC limits LPCVD PolySi 4"](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_polysilicon/Deposition_of_polysilicon_using_LPCVD/Standard_recipes%2C_QC_limits_and_results_for_the_4%22_polysilicon_furnace) |
| **LPCVD PolySi 6”**QC data limits | **Pernille V. Larsen@ danchip** | [QC limits LPCVD PolySi 6"](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_polysilicon/Deposition_of_polysilicon_using_LPCVD/Standard_recipes%2C_QC_limits_and_results_for_the_6%22_polysilicon_furnace) |
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